Patent Claims

1. Component, which comprises a substrate and at least one upper and one lower insulating layer, which are adjacent to each other and whose layer thickness is in the range of between 0.05 and 50 μm, at least one region of one insulating layer being activated for subsequent metallization, for photosensitization, for hydrophobicization and/or for other surface functionalization.

2. Component according to Claim 1, which is an electronic or microelectronic component.

3. Component according to one of the preceding claims, which comprises two chemically different insulating layers.

4. Component according to one of the preceding claims, in which an upper layer is patterned and/or is the mask for the activation of the lower layer.

5. Component according to one of the preceding claims, in which the activated regions are seeded and/or metallized.

6. Process for the production of a component, a lower insulating layer being applied to a substrate and optionally patterned in a first working step, at least one region of the

lower insulating layer being activated in a second working step and at least one second, upper insulating layer being applied to the lower, activated insulating layer and patterned in a third working step.

7. Process according to Claim 6, in which at least one insulating layer is patterned following its application.

8. Process for the production of a component, an insulating layer being applied to a substrate and optionally patterned in a first working step, a further insulating layer being applied and patterned in a second working step, and one of the two insulating layers being activated in a third working step.

9. Process according to Claim 8, in which the second insulating layer is patterned after the second working step and before the third working step.

10. Process according to one of Claims 8 and 9, in which the lower insulating layer is patterned after the first working step.